



VMDSEMI

VUSB010R66BNA

Datasheet



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General Description
Symbol

$V_{(BR)DSS}$	$R_{DS(ON)_{max}}$	I_D
100V	6.6Ω@10V	0.17A
	7.5Ω@4.5V	

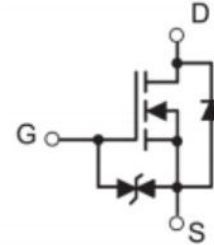
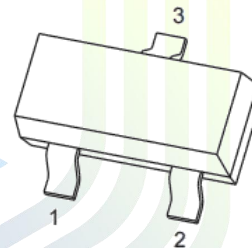


Figure 1 Symbol of VUSB010R66BNA

Features

- Surface Mount Package
- High Density Cell Design for Extremely Low $R_{DS(ON)}$
- Voltage Controlled Small Signal Switch
- Rugged and Reliable
- ESD protected Gate

Package Type


1. GATE
2. SOURCE
3. DRAIN

SOT-23
Application

- Small Servo Motor Controls
- Power MOSFET Gate Drivers
- Switching Application

Figure 2 Package Type of VUSB010R66BNA

Ordering Information

Product Name	Package
VUSB010R66BNA	SOT-23

6.6Ω, 100V, N-Channel Power MOSFET
VUSB010R66BNA
Absolute Maximum Ratings ($T_A = 25\text{ }^\circ\text{C}$, unless otherwise specified)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DSS}	100	V
Gate-Source Voltage	V_{GSS}	± 20	V
Continuous Drain Current ^{Note1}	I_D	0.17	A
Pulsed Drain Current ^{Note2}	I_{DM}	0.68	
Total Power Dissipation ^{Note4}	P_D	0.35	W
Junction Temperature	T_J	150	$^\circ\text{C}$
Storage Temperature	T_{STG}	-55 to 150	$^\circ\text{C}$

Thermal Resistance

Parameter	Symbol	Min	Typ	Max	Unit
Thermal Resistance, Junction-to-Ambient ^{Note5}	$R_{\theta JA}$		357		$^\circ\text{C/W}$

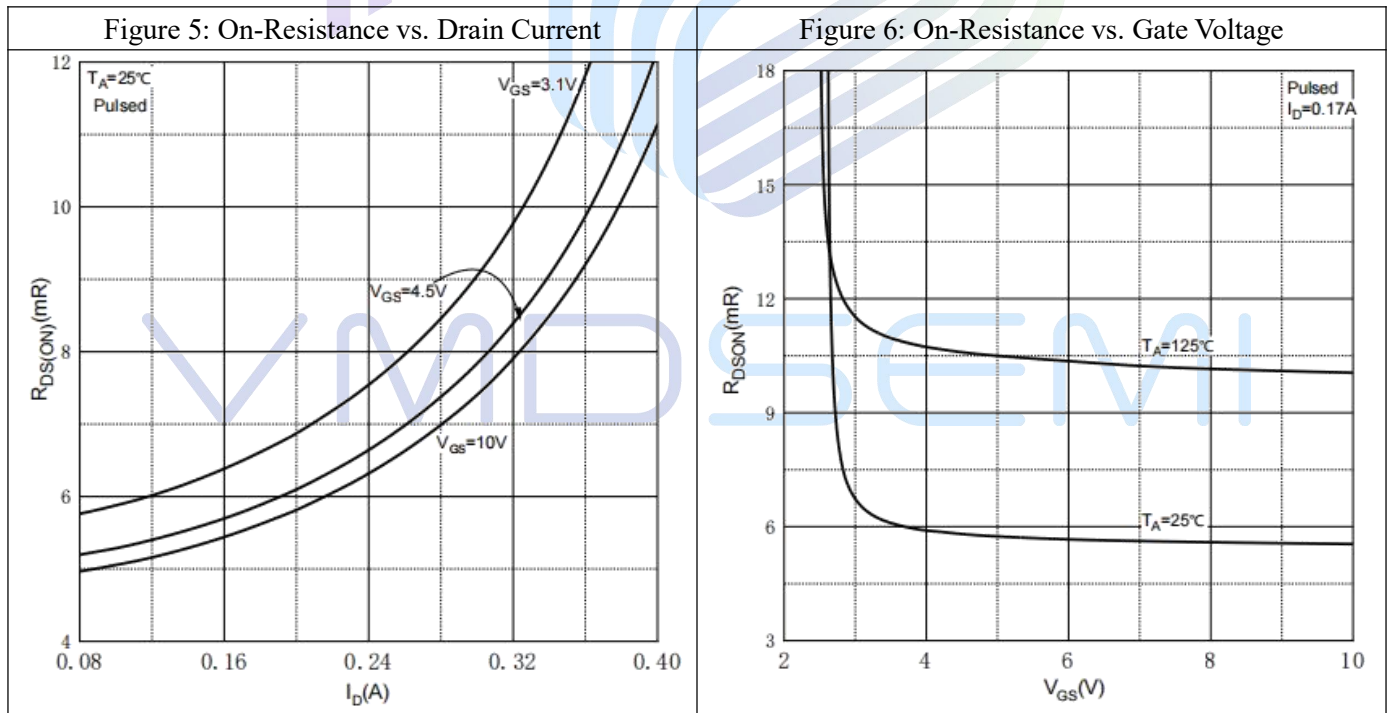
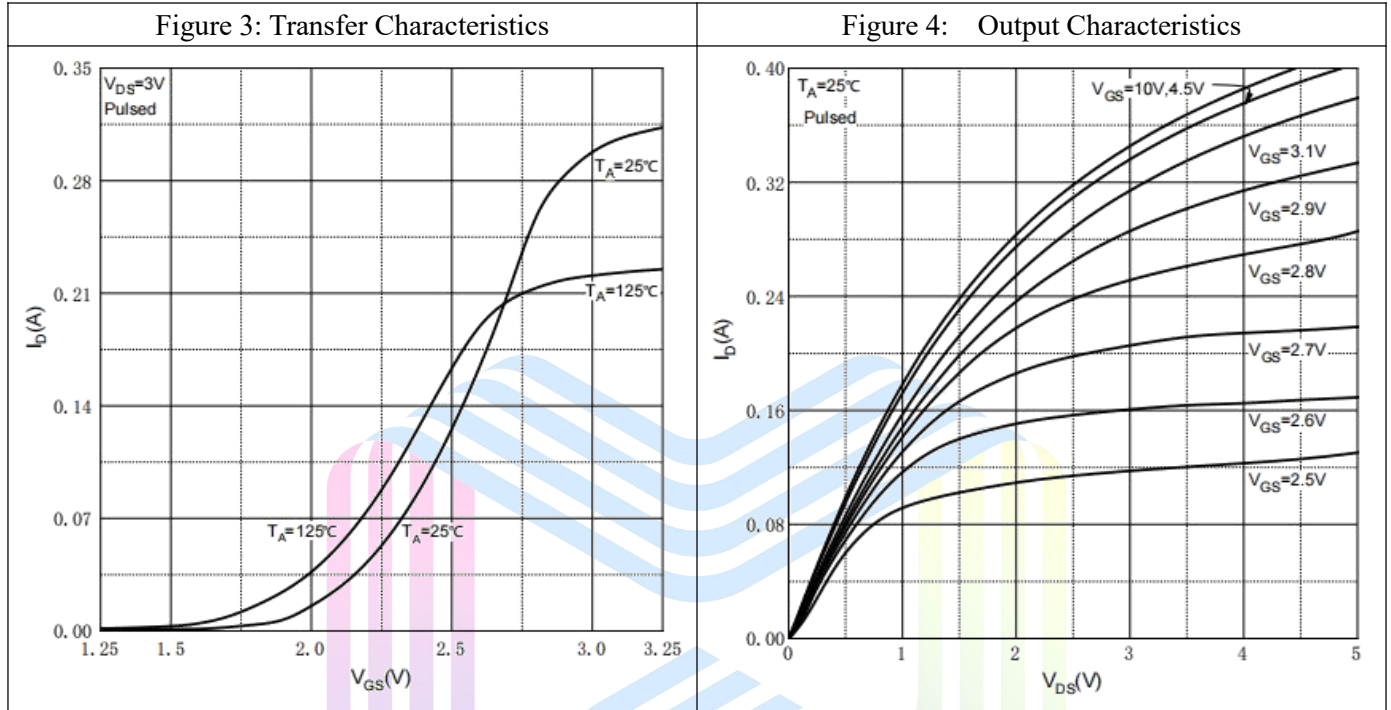


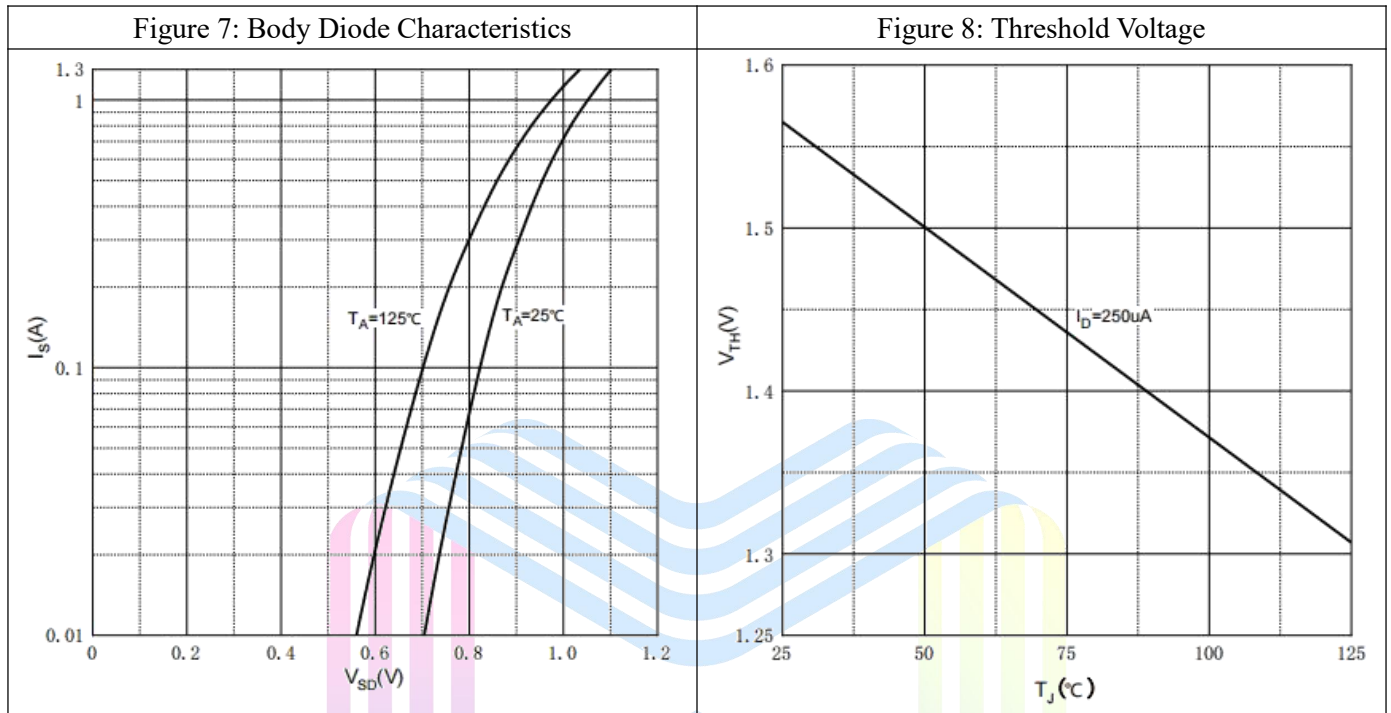
6.6Ω, 100V, N-Channel Power MOSFET
VUSB010R66BNA
Electrical Characteristics ($T_A = 25\text{ }^\circ\text{C}$, unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Statistic Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu A$	100			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=100V, V_{GS}=0V$			1	μA
Gate-Body Leakage Current	I_{GSS}	$V_{GS} = \pm 20V, V_{DS}=0V$			± 5	μA
Gate Threshold Voltage ^{Note3}	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	1	1.6	3	V
Static Drain-Source On-Resistance ^{Note3}	$R_{DS(ON)}$	$V_{GS}=10V, I_D=0.17A$		5.5	6.6	Ω
		$V_{GS}=4.5V, I_D=0.17A$		5.9	7.5	
Forward Transconductance ^{Note3}	g_{FS}	$V_{DS}=10V, I_D=0.17A$	80			S
Dynamic Characteristics						
Input Capacitance	C_{ISS}	$V_{DS}=45V$		19		pF
Output Capacitance	C_{OSS}	$V_{GS}=0V$		3.4		pF
Reverse Transfer Capacitance	C_{RSS}	$f=1MHz$		1.8		pF
Total Gate Charge	Q_g	$V_{DS}=10V$		1.4		nC
Gate-Source Charge	Q_{gs}	$V_{GS}=10V$		0.15		
Gate-Drain Charge	Q_{gd}	$I_D=0.22A$		0.2		
Switching Parameters						
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=30V$		8		ns
Turn-on Rise Time	t_r	$V_{GS}=10V$		8		
Turn-off Delay Time	$t_{d(off)}$	$I_D=0.28A$		13		
Turn-off Fall Time	t_f	$R_G=50\Omega$		16		
Diode Characteristics						
Diode Forward Voltage ^{Note3}	V_{SD}	$V_{GS}=0V, I_S=0.17A$		0.8	1.3	V

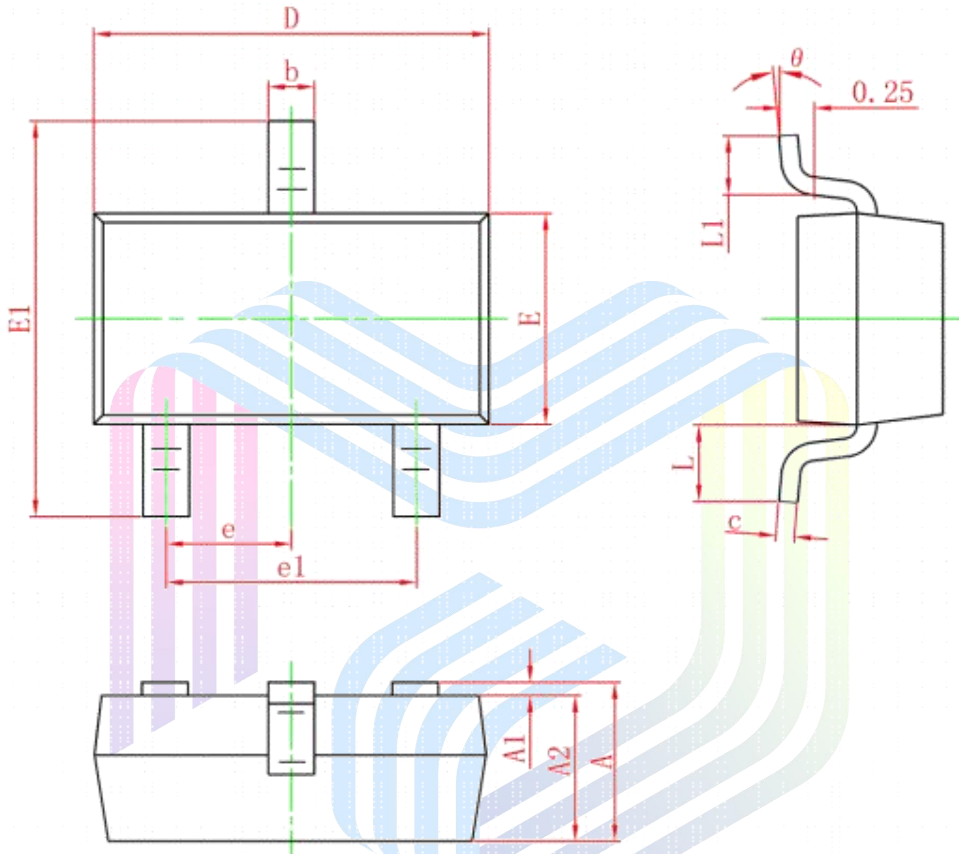
Notes :

1. The maximum current rating is limited by package. And device mounted on a large heatsink.
2. Pulse Test : Pulse Width $\leq 10\mu s$, duty cycle $\leq 1\%$.
3. Pulse Test : Pulse Width $\leq 380\mu s$, duty cycle $\leq 2\%$.
4. The power dissipation P_D is limited by $T_{J(MAX)} = 150^\circ\text{C}$. And device mounted on a large heatsink
5. Device mounted on 1in2 FR-4 board with 1oz. Copper, in a still air environment with $T_A = 25^\circ\text{C}$.

Typical Performance Characteristics




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Mechanical Dimensions:
SOT-23 Package Information


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.150	0.035	0.045
A1	0	0.100	0	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.150	1.500	0.045	0.059
E1	2.250	2.650	0.089	0.104
e	0.950TYP		0.037TYP	
e1	1.800	2.000	0.071	0.079
L	0.550REF		0.022REF	
L1	0.300	0.500	0.012	0.020
θ	0°	8°	0°	8°

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